

Master Bond EP21 Room Temperature Curing Epoxy System

Category : Polymer , Adhesive , Thermoset , Epoxy , Epoxy Adhesive

Material Notes:

Room temperature curing epoxy adhesive Master Bond EP21 has outstanding physical properties and durability. Its variable mix ratio feature allows you to adjust the type of cure to get either a more rigid cure for enhanced machineability, or a more forgiving cure for greater impact resistance. EP21 conforms to Title 21, US Code of Federal Regulations, FDA Chapter 1 Section 175.105.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Master-Bond-EP21-Room-Temperature-Curing-Epoxy-System.php

Physical Properties	Metric	English	Comments
Viscosity	50000 - 60000 cP	50000 - 60000 cP	
	@Temperature 23.0 °C	@Temperature 73.4 °F	

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	121 °C	250 °F	
Minimum Service Temperature, Air	-51.1 °C	-60.0 °F	

Processing Properties	Metric	English	Comments
Cure Time	120 min	2.00 hour	
	@Temperature 93.3 °C	@Temperature 200 °F	
	1440 - 2880 min	24.0 - 48.0 hour	
	@Temperature 23.0 °C	@Temperature 73.4 °F	

Descriptive Properties	Value	Comments
Color Code	"A" Gray; "B" Tan	
Mix Ratio By Weight	100/100	
Set-Up Time, minutes	60-90	At Room Temperature

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